

Application No.: 09/811,667
Docket No.: 5957/Consilium/MBE



JFW
PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Yuan, et al. :
Serial No. 09/811,667 : Group Art Unit: 3623
Filed: March 20, 2001 : Examiner: JARRETT, Scott L.
For: Fault Tolerant and Automated Computer Software Workflow

RE-SUBMITTAL OF INFORMATION DISCLOSURE STATEMENTS

Honorable Commissioner for Patents
Alexandria, VA 22313-1450

Sir:

This is a re-submittal of Information Disclosure Statements ("IDSes"). In the Office Action dated February 4, 2005 (the "Office Action"), the Examiner stated that IDSes filed on October 3, 2001, September 19, 2002, November 19, 2002, December 31, 2002, April 25, 2003, July 3, 2003, October 9, 2003, December 18, 2003, March 29, 2004, August 11, 2004, October 8, 2004, and December 7, 2004 failed to comply with 37 CFR 1.98(a)(2), "which requires a legible copy of each U.S. and foreign patent; each publication of that portion which caused it to be listed; and all other information or that portion which caused it to be listed." (Paragraph 4 of the Office Action.)

Applicants believe a legible copy of each listed reference was submitted with the above-cited IDSes. However, in order to expedite the prosecution of the present application, Applicants are resubmitting clean copies of all references crossed out by the Examiner as not considered. Applicants are also resubmitting clean copies of Form PTO-1449. The Examiner is respectfully requested to consider the resubmitted references, initial the Form PTO-1449 for the resubmitted references, and return the initialized Form PTO-1449 to Applicants.


AUTHORIZATION

The Commissioner is hereby authorized to charge any additional fees, which may be required for this Amendment, or credit any overpayment to deposit account no. 08-0219.

In the event that an extension of time is required, or which may be required in addition to that requested in a petition for an extension of time, the Commissioner is requested to grant a petition for that extension of time which is required to make this response timely and is hereby authorized to charge any fee for such an extension of time or credit any overpayment for an extension of time to deposit account no. 08-0219.

Respectfully submitted,

WILMER CUTLER PICKERING HALE AND DORR LLP



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Date: Sept 30, 2005
AHK:cj 107262.142 US1

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION**

(PTO-1449)

ATTY. DOCKET NO.
5957/Consilium/MBE

SERIAL NO.
09/811,667

RECEIVED
OCT 05 2001
Technology Center 2100

APPLICANT
Huey-Shin YUAN et al.

FILING DATE
March 20, 2001

GROUP
2163

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	4,796,194	01/03/89	Atherton			08/20/86
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
	5,295,242	03/15/94	Mashruwala et al.			11/02/90
	5,309,221	05/03/94	Fischer et al.			12/31/91
	5,367,624	11/22/94	Cooper			06/11/93
	5,398,336	03/14/95	Tantry et al.			06/16/93
	5,402,367	03/28/95	Sullivan et al.			07/19/93
	5,408,405	04/18/95	Mozumder et al.			09/20/93
	5,410,473	04/25/95	Kaneko et al.			12/16/92
	5,490,097	02/06/96	Swenson et al.			08/06/93
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	HEI 1-283934	11/15/89	Japan			X	
	HEI 8-149583	06/07/96	Japan			X	
	HEI 9-34535	02/07/97	Japan			X	
	EP 0877308	11/11/98	Europe			X	
	HEI 11-67853	03/09/99	Japan			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Dishon, G., D. Eylon, M. Finarov, and A. Shulman. "Dielectric CMP Advanced Process Control Based on Integrated Monitoring." Ltd. Rehoveth, Israel: Nova Measuring Instruments.

Runyan, W. R., and K. E. Bean. 1990. "Semiconductor Integrated Circuit Processing Technology." pg. 48. Reading, Massachusetts: Addison-Wesley Publishing Company.

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	5,661,669	08/26/97	Mozumder et al.			06/07/95
	5,698,989	12/16/97	Nulman			09/13/96
	5,719,495	02/17/98	Moslehi			06/05/96
	5,740,429	04/14/98	Wang et al.			07/07/95
	5,751,582	05/12/98	Saxena et al.			09/24/96
	5,754,297	05/19/98	Nulman			04/14/97
	5,764,543	06/09/98	Kennedy			06/16/95
	5,808,303	09/15/98	Schlagheck et al.			01/29/97
	5,883,437	03/16/99	Maruyama et al.			12/28/95
	5,910,011	06/08/99	Cruse			05/12/97
	6,054,379	04/25/00	Yau et al.			02/11/98

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OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.
	Rampalli, Prasad, Arakere Ramesh, and Nimish Shah. 1991. CEPT—A Computer-Aided Manufacturing Application for Managing Equipment Reliability and Availability in the Semiconductor Industry. New York, New York: IEEE.
	Moyne, James R., Nauman Chaudhry, and Roland Telfeyan. 1995. "Adaptive Extensions to a Multi-Branch Run-to-Run Controller for Plasma Etching." <i>Journal of Vacuum Science and Technology</i> . Ann Arbor, Michigan: University of Michigan Display Technology Manufacturing Center.
	Moyne, James, Roland Telfeyan, Arnon Hurwitz, and John Taylor. August 1995. "A Process-Independent Run-to-Run Controller and Its Application to Chemical-Mechanical Planarization." <i>SEMI/IEEE Advanced Semiconductor Manufacturing Conference and Workshop</i> . Ann Arbor, Michigan: The University of Michigan, Electrical Engineering & Computer Science Center for Display Technology & Manufacturing.



EXAMINER

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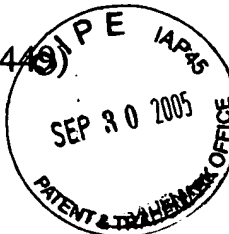
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 5957/Consilium/MBE		SERIAL NO. 09/811,667	
 				APPLICANT Huey-Shin YUAN et al.			
				FILING DATE March 20, 2001		GROUP 2163	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation	
						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 th Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 st International CMP Planarization Conference.						
	SEMI. [1986] 1996. "Standard for Definition and Measurement of Equipment Reliability, Availability, and Maintainability (RAM)." SEMI E10-96.						
	Van Zant, Peter. 1997. <i>Microchip Fabrication: A Practical Guide to Semiconductor Processing</i> . Third Edition, pp. 472-478. New York, New York: McGraw-Hill.						
	Campbell, W. Jarrett, and Anthony J. Toprac. February 11-12, 1998. "Run-to-Run Control in Microelectronics Manufacturing." Advanced Micro Devices, TWMCC.						
	Consilium. August 1998. <i>Quality Management Component: QMC™ and QMC-Link™ Overview</i> . Mountain View, California: Consilium, Inc.						
	Consilium. 1998. <i>FAB300™</i> . Mountain View, California: Consilium, Inc.						
	Khan, Kareemullah, Victor Solakhain, Anthony Ricci, Tier Gu, and James Moyne. 1998. "Run-to-Run Control of ITO Deposition Process." Ann Arbor, Michigan.						
	Moyne, James and John Curry. June 1998. "A Fully Automated Chemical-Mechanical Planarization Process."						
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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS	
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	Translation	
						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	SEMI. July 1998. <i>New Standard: Provisional Specification for CIM Framework Domain Architecture</i> . Mountain View, California: SEMI Standards. SEMI Draft Doc. 2817.						
	Consilium. July 1999. "Increasing Overall Equipment Effectiveness (OEE) in Fab Manufacturing by Implementing Consilium's Next-Generation Manufacturing Execution System - MES II." Semiconductor Fabtech Edition 10.						
	Consilium Corporate Brochure. October 1999. www.consilium.com						
	Consilium. January 1999. "FAB300™: Consilium's Next Generation MES Solution of Software and Services which Control and Automate Real-Time FAB Operations." www.consilium.com/products/fab300_page.htm#FAB300 Introduction						
	Consilium. November 1999. <i>FAB300™ Update</i> .						
	SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000.						
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;">  </div> <div style="text-align: center;">  </div> </div>				ATTY. DOCKET NO. 5957/Consilium/MBE		SERIAL NO. 09/811,667	
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				APPLICANT Huey-Shin YUAN et al.			
FILING DATE March 20, 2001				GROUP 2163			

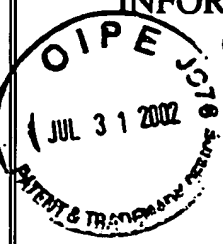

U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO./ PUBLICATION NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,329,463	07/12/94	Sierk et al.			01/13/93
	5,495,417	02/27/96	Fuduka et al.			03/16/93
	5,497,316	03/05/96	Sierk et al.			04/04/95
	5,503,707	04/02/96	Maung et al.			09/22/93
	5,508,947	04/16/96	Sierk et al.			05/13/94
	5,657,254	08/12/97	Sierk et al.			04/15/96
	5,694,325	12/02/97	Fukuda et al.			11/22/95
	5,838,595	11/17/98	Sullivan et al.			11/25/96

FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	05-151231	06/18/93	Japan				X
	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
	1072967A3	11/21/01	Europe			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	

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						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.						
	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 nd National Symposium of the American Vacuum Society.						
	Chang, E., B. Stine, T. Maung, R. Divecha, D. Boning, J. Chung, K. Chang, G. Ray, D. Bradbury, O. S. Nakagawa, S. Oh, and D. Bartelink. December 1995. "Using a Statistical Metrology Framework to Identify Systematic and Random Sources of Die- and Wafer-level ILD Thickness Variation in CMP Processes." Washington, D.C.: International Electron Devices Meeting.						
	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Santa Clara, California: VLSI Multilevel Interconnect Conference.						
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						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
Boning, Duane, William Moyne, Taber Smith, James Moyne, Roland Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." <i>IEEE Trans. CPMT (C)</i> , Vol. 19, No. 4, pp. 307-314.							
Edgar, Thomas F., Stephanie W. Butler, Jarrett Campbell, Carlos Pfeiffer, Chris Bode, Sung Bo Hwang, and K.S. Balakrishnan. May 1998. "Automatic Control in Microelectronics Manufacturing: Practices, Challenges, and Possibilities." <i>Automatica</i> , Vol. 36, pp. 1567-1603, 2000.							
Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. November 1998. "Multizone Uniformity Control of a CMP Process Utilizing a Pre and Post-Measurement Strategy." Seattle, Washington: SEMETECH Symposium.							
Moyne, James. October 1999. "Advancements in CMP Process Automation and Control." Hawaii: (Invited paper and presentation to) Third International Symposium on Chemical Mechanical Polishing in IC Device Manufacturing: 196 th Meeting of the Electrochemical Society.							
Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulus, Dale Hetherington, HongJiang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting.							
NovaScan 2020. February 2002. "Superior Integrated Process Control for Emerging CMP High-End Applications."							
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	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,208,765	05/04/93	Turnbull			07/20/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,420,796	05/30/95	Weling et al.			12/23/93
	5,469,361	11/21/95	Moyne			06/06/94
	5,525,808	06/11/96	Irie et al.			12/20/94
	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,664,987	09/09/97	Renteln			09/04/96
	5,812,407	09/22/98	Sato et al.			08/12/97
	5,828,778	10/27/98	Hagi et al.			06/12/96
	5,832,224	11/03/98	Fehskens et al.			06/14/96

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GROUP 3600

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						Yes	No
/	61-171147	08/01/86	Japan				X
/	6-184434	07/05/94	Japan				X
/	0 621 522 A2	10/26/94	Europe			X	
/	8-50161	02/20/96	Japan				X
/	8-304023	11/22/96	Japan				X

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

February 1984. "Method and Apparatus of in Situ Measurement and Overlay Error Analysis for Correcting Step and Repeat Lithographic Cameras." *IBM Technical Disclosure Bulletin*, pp. 4855-4859.

October 1984. "Method to Characterize the Stability of a Step and Repeat Lithographic System." *IBM Technical Disclosure Bulletin*, pp. 2857-2860.

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	5,859,964	01/12/99	Wang et al.			10/25/96
	5,863,807	01/26/99	Jang et al.			03/15/96
	5,870,306	02/09/99	Harada			06/13/97
	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,963,881	10/05/99	Kahn et al.			10/20/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
	6,078,845	06/20/00	Friedman			11/25/96
	6,112,130	08/29/00	Fukuda et al.			10/01/97
	6,148,246	11/14/00	Kawazome			06/10/98

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GROUP 3600

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						Yes	No
/	0 747 795 A2	12/11/96	Europe			X	
/	10-173029	06/26/98	Japan				X
/	0 895 145 A1	02/03/99	Europe			X	
/	11-126816	05/11/99	Japan				X

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Schmid, Hans Albrecht. 1995. "Creating the Architecture of a Manufacturing Framework by Design Patterns." Austin, Texas: OOPSLA.

Baliga, John. July 1999. "Advanced Process Control: Soon to be a Must." Cahners Semiconductor International. www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	6,175,777	01/16/01	Kim			01/16/98	
	6,178,390	01/23/01	Jun			09/08/98	
	6,185,324	02/06/01	Ishihara et al.			01/31/95	
	6,192,291	02/20/01	Kwon			10/08/98	
	6,197,604	03/06/01	Miller et al.			10/01/98	
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	11-135601	05/21/99	Japan				X
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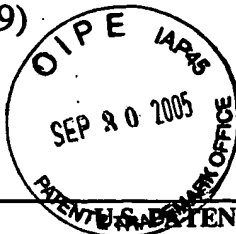
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09/811,667

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Huey-Shin YUAN et al.

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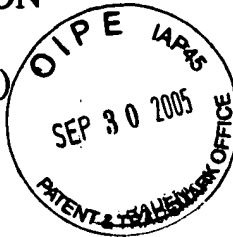
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	0 869 652	10/07/98	Europe			X	
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INFORMATION DISCLOSURE
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(PTO-1449)

ATTY. DOCKET NO.
005957
USA/Consilium/Consilium

SERIAL NO.
09/811,667

APPLICANT
Huey-Shin YUAN et al.

FILING DATE
March 20, 2001

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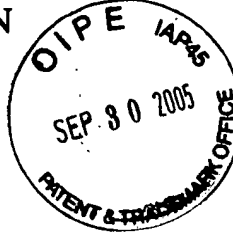
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Huey-Shin YUAN et al.

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SHEET 1 OF 4

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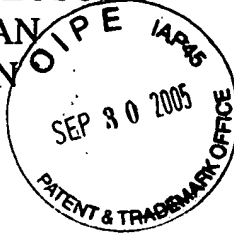
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APPLICANT
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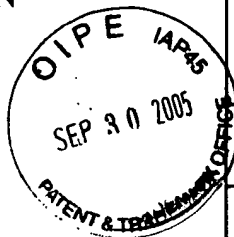
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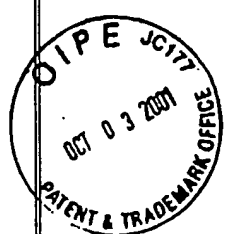
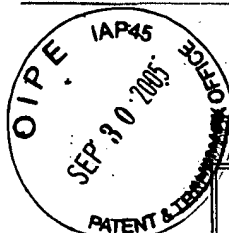
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				APPLICANT Huey-Shin YUAN et al.			
				FILING DATE March 20, 2001		GROUP 2163	
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		APPLICANT Huey-Shin YUAN et al.	
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	August 24, 2004. Office Action for U.S. Serial No. 10/135,405, filed May 1, 2002.		
	August 25, 2004. Office Action for U.S. Serial No. 09/998,384, filed November 30, 2001.		
	September 9, 2004. Written Opinion for PCT Serial No. PCT/US02/21942.		
	September 16, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/24859.		
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SHEET 1 OF 4

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ATTY. DOCKET NO.
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
A	4,796,194	01/03/89	Atherton			08/20/86
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
	5,295,242	03/15/94	Mashruwala et al.			11/02/90
	5,309,221	05/03/94	Fischer et al.			12/31/91
	5,367,624	11/22/94	Cooper			06/11/93
	5,398,336	03/14/95	Tantry et al.			06/16/93
	5,402,367	03/28/95	Sullivan et al.			07/19/93
	5,408,405	04/18/95	Mozumder et al.			09/20/93
	5,410,473	04/25/95	Kaneko et al.			12/16/92
V	5,490,097	02/06/96	Swenson et al.			08/06/93
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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A	HEI 1-283934	11/15/89	Japan			X	
	HEI 8-149583	06/07/96	Japan			X	
	HEI 9-34535	02/07/97	Japan			X	
	EP 0877308	11/11/98	Europe			X	
	HEI 11-87853	03/09/99	Japan			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

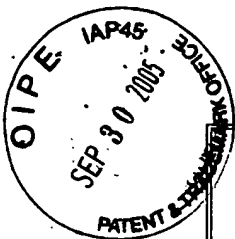
	Dishon, G., D. Eylon, M. Finarov, and A. Shulman. "Dielectric CMP Advanced Process Control Based on Integrated Monitoring." Ltd. Rehoveth, Israel: Nova Measuring Instruments.
	Runyan, W. R., and K. E. Bean. 1990. "Semiconductor Integrated Circuit Processing Technology." pg. 48. Reading, Massachusetts: Addison-Wesley Publishing Company.

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SHEET 2 OF 4

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
[Signature]	5,661,669	08/26/97	Mozumder et al.			06/07/95
	5,698,989	12/16/97	Nulman			09/13/96
	5,719,495	02/17/98	Moslehi			06/05/96
	5,740,429	04/14/98	Wang et al.			07/07/95
	5,751,582	05/12/98	Saxena et al.			09/24/96
	5,754,297	05/19/98	Nulman			04/14/97
	5,764,543	06/09/98	Kennedy			06/16/95
	5,808,303	09/15/98	Schlagheck et al.			01/29/97
	5,883,437	03/16/99	Maruyama et al.			12/28/95
	5,910,011	06/08/99	Cruse			05/12/97
	6,054,379	04/25/00	Yau et al.			02/11/98

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	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.
	Rampalli, Prasad, Arakere Ramesh, and Nimish Shah. 1991. CEPT—A Computer-Aided Manufacturing Application for Managing Equipment Reliability and Availability in the Semiconductor Industry. New York, New York: IEEE.
	Moyne, James R., Nauman Chaudhry, and Roland Telfeyan. 1995. "Adaptive Extensions to a Multi-Branch Run-to-Run Controller for Plasma Etching." <i>Journal of Vacuum Science and Technology</i> . Ann Arbor, Michigan: University of Michigan Display Technology Manufacturing Center.
	Moyne, James, Roland Telfeyan, Arnon Hurwitz, and John Taylor. August 1995. "A Process-Independent Run-to-Run Controller and Its Application to Chemical-Mechanical Planarization." <i>SEMI/IEEE Advanced Semiconductor Manufacturing Conference and Workshop</i> . Ann Arbor, Michigan: The University of Michigan, Electrical Engineering & Computer Science Center for Display Technology & Manufacturing.

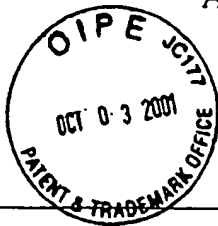
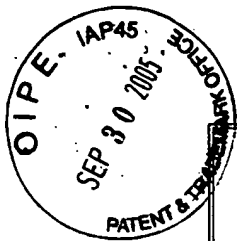
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SHEET 3 OF 4

INFORMATION DISCLOSURE
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
A	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	Translation
						Yes No

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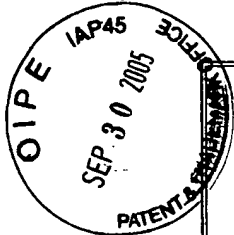
	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 th Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 st International CMP Planarization Conference.
	SEMI. [1986] 1996. "Standard for Definition and Measurement of Equipment Reliability, Availability, and Maintainability (RAM)." SEMI E10-96.
	Van Zant, Peter. 1997. <i>Microchip Fabrication: A Practical Guide to Semiconductor Processing</i> . Third Edition, pp. 472-478. New York, New York: McGraw-Hill.
	Campbell, W. Jarrett, and Anthony J. Toprac. February 11-12, 1998. "Run-to-Run Control in Microelectronics Manufacturing." <i>Advanced Micro Devices, TWMCC</i> .
	Consilium. August 1998. <i>Quality Management Component: QMC™ and QMC-Link™ Overview</i> . Mountain View, California: Consilium, Inc.
	Consilium. 1998. <i>FAB300™</i> . Mountain View, California: Consilium, Inc.
	Khan, Kareemullah, Victor Solakhain, Anthony Ricci, Tier Gu, and James Moyne. 1998. "Run-to-Run Control of ITO Deposition Process." Ann Arbor, Michigan.
	Moyne, James and John Curry. June 1998. "A Fully Automated Chemical-Mechanical Planarization Process."

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SHEET 4 OF 4

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		

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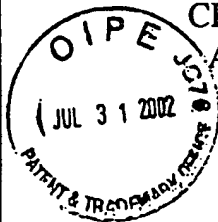
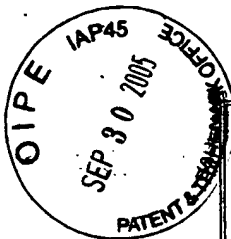
	SEMI. July 1998. New Standard: Provisional Specification for CIM Framework Domain Architecture. Mountain View, California: SEMI Standards. SEMI Draft Doc. 2817.
	Consilium. July 1999. "Increasing Overall Equipment Effectiveness (OEE) in Fab Manufacturing by Implementing Consilium's Next-Generation Manufacturing Execution System - MES II." Semiconductor Fabtech Edition 10.
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	Consilium. November 1999. FAB300™ Update.
	SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000.

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EXAMINER'S INITIALS	PATENT NO/ PUBLICATION NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
J	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,329,463	07/12/94	Sierk et al.			01/13/93
	5,495,417	02/27/96	Fuduka et al.			03/16/93
	5,497,316	03/05/96	Sierk et al.			04/04/95
	5,503,707	04/02/96	Maung et al.			09/22/93
	5,508,947	04/16/96	Sierk et al.			05/13/94
	5,657,254	08/12/97	Sierk et al.			04/15/96
	5,694,325	12/02/97	Fukuda et al.			11/22/95
	5,838,595	11/17/98	Sullivan et al.			11/25/96

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J	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	05-151231	06/18/93	Japan				X
	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
J	1072967A3	11/21/01	Europe			X	

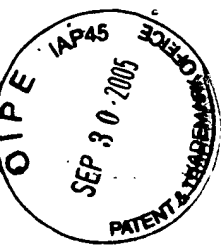
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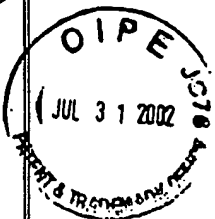
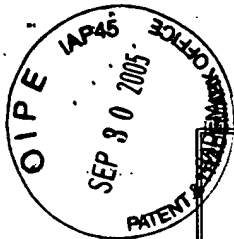
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 5957/Consilium/MBE		SERIAL NO. 09/811,667	
				APPLICANT Huey-Shin YUAN et al.			
				FILING DATE March 20, 2001		GROUP 2163	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT/ PUBLICATION NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.						
	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 nd National Symposium of the American Vacuum Society.						
	Chang, E., B. Stine, T. Maung, R. Divecha, D. Boning, J. Chung, K. Chang, G. Ray, D. Bradbury, O. S. Nakagawa, S. Oh, and D. Bartelink. December 1995. "Using a Statistical Metrology Framework to Identify Systematic and Random Sources of Die- and Wafer-level ILD Thickness Variation in CMP Processes." Washington, D.C.: International Electron Devices Meeting.						
	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Santa Clara, California: VLSI Multilevel Interconnect Conference.						
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE

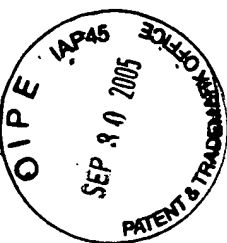
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EXAMINER'S INITIALS	PATENT/ PUBLICATION NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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B	Boning, Duane, William Moyne, Taber Smith, James Moyne, Roland Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." <i>IEEE Trans. CPMT (C)</i> , Vol. 19, No. 4, pp. 307-314.
	Edgar, Thomas F., Stephanie W. Butler, Jarrett Campbell, Carlos Pfeiffer, Chris Bode, Sung Bo Hwang, and K.S. Balakrishnan. May 1998. "Automatic Control in Microelectronics Manufacturing: Practices, Challenges, and Possibilities." <i>Automatica</i> , Vol. 36, pp. 1567-1603, 2000.
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	Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulos, Dale Hetherington, HongJiang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting.
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AS	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,208,765	05/04/93	Turnbull			07/20/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,420,796	05/30/95	Weling et al.			12/23/93
	5,469,361	11/21/95	Moyne			06/06/94
	5,525,808	06/11/96	Irie et al.			12/20/94
	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,664,987	09/09/97	Renteln			09/04/96
	5,812,407	09/22/98	Sato et al.			08/12/97
	5,828,778	10/27/98	Hagi et al.			06/12/96
	5,832,224	11/03/98	Fehskens et al.			06/14/96

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AS	61-171147	08/01/86	Japan				X
AS	6-184434	07/05/94	Japan				X
AS	0 621 522 A2	10/26/94	Europe			X	
AS	8-50161	02/20/96	Japan				X
AS	8-304023	11/22/96	Japan				X

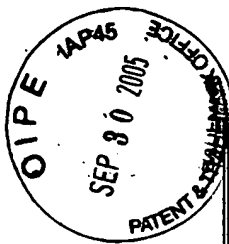
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AS	February 1984. "Method and Apparatus of in Situ Measurement and Overlay Error Analysis for Correcting Step and Repeat Lithographic Cameras." <i>IBM Technical Disclosure Bulletin</i> , pp. 4855-4859.
AS	October 1984. "Method to Characterize the Stability of a Step and Repeat Lithographic System." <i>IBM Technical Disclosure Bulletin</i> , pp. 2857-2860.

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<i>[initials]</i>	5,859,964	01/12/99	Wang et al.			10/25/96
	5,863,807	01/26/99	Jang et al.			03/15/96
	5,870,306	02/09/99	Harada			06/13/97
	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,963,881	10/05/99	Kahn et al.			10/20/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
<i>[initials]</i>	6,078,845	06/20/00	Friedman			11/25/96
	6,112,130	08/29/00	Fukuda et al.			10/01/97
	6,148,246	11/14/00	Kawazome			06/10/98

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<i>[initials]</i>	0 747 795 A2	12/11/96	Europe			X	
	10-173029	06/26/98	Japan				X
<i>[initials]</i>	0 895 145 A1	02/03/99	Europe			X	
	11-126816	05/11/99	Japan				X

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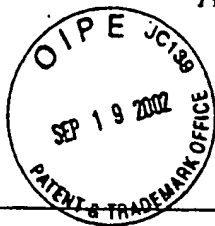
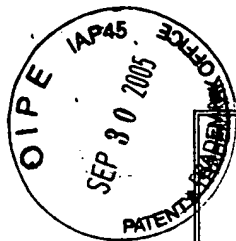
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SHEET 3 OF 4

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		ATTY. DOCKET NO. 5957/Consilium/MBE	SERIAL NO. 09/811,667
		APPLICANT Huey-Shin YUAN et al.	
		FILING DATE March 20, 2001	GROUP 2163

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
D	6,175,777	01/16/01	Kim			01/16/98
	6,178,390	01/23/01	Jun			09/08/98
	6,185,324	02/06/01	Ishihara et al.			01/31/95
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	6,211,094	04/03/01	Jun et al.			08/23/99
	6,226,792	05/01/01	Goiffon et al.			10/14/98
	6,230,069	05/08/01	Campbell et al.			06/26/98
	6,236,903	05/22/01	Kim et al.			09/25/98
	6,240,330	05/29/01	Kurtzberg et al.			05/28/97

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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D	H-135601	05/21/99	Japan				X
	WO 00/05759	02/03/00	WO			X	
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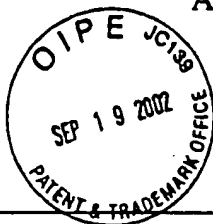
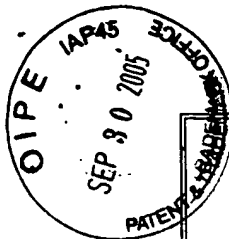
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SHEET 4 OF 4

INFORMATION DISCLOSURE
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APPLICATION
(PTO-1449)ATTY. DOCKET NO.
5957/Consilium/MBESERIAL NO.
09/811,667APPLICANT
Huey-Shin YUAN et al.FILING DATE
March 20, 2001GROUP
2163

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	6,240,331	05/29/01	Yun			08/18/98
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	6,252,412	06/26/01	Talbot et al.			01/08/99
	6,263,255	07/17/01	Tan et al.			05/18/98
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	6,298,274	10/02/01	Inoue			09/01/99
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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/	WO 00/79355 A1	12/28/00	WO			X	
/	2001-76982	03/23/01	Japan				X
/	WO 01/33501 A1	05/10/01	WO			X	

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SHEET 1 OF 1

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(PTO-1449)

ATTY. DOCKET NO.
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USA/Consilium/Consilium

SERIAL NO.
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APPLICANT
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19	2 347 885 A	09/20/00	GB			X	
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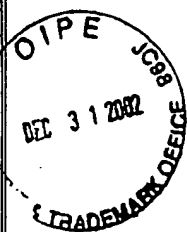
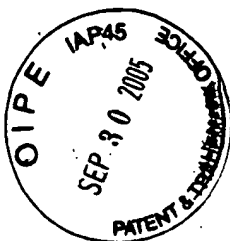
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SHEET 1 OF 2

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 005957 USA/Consilium/Consilium		SERIAL NO. 09/811,667	
				APPLICANT Huey-Shin YUAN et al.			
				FILING DATE March 20, 2001		GROUP 2163	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	5,844,554	12/01/98	Geller et al.			09/17/96	
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JD	WO 95/34866	12/21/95	WO			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	WO 99/25520	05/27/99	WO			X	
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INFORMATION DISCLOSURE
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SERIAL NO.
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APPLICANT
Huey-Shin YUAN et al.

FILING DATE
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GROUP
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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>[initials]</i>	5,889,991	03/30/99	Consolatti et al.			12/06/96
	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
<i>[initials]</i>	6,298,470 B1	10/02/01	Breiner et al.			04/15/99

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<i>[initials]</i>	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
<i>[initials]</i>	WO 02/33737 A2	04/25/02	WO			X	

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<i>[initials]</i>	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
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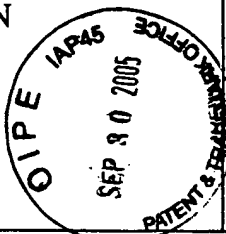
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Huey-Shin YUAN et al.

FILING DATE
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
g	3,205,485	09/07/65	Noltingk			10/21/60
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	5,283,141	02/01/94	Yoon et al.			03/05/92
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	5,511,005	04/23/96	Abbe et al.			02/16/94
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	5,553,195	09/03/96	Meijer			09/29/94
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>NY</i>	5,667,424	09/16/97	Pan			09/25/96
	5,674,787	10/07/97	Zhao et al.			01/16/96
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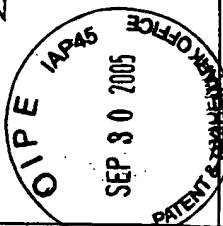
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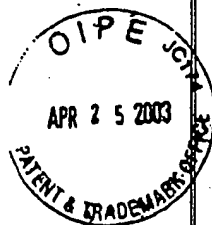
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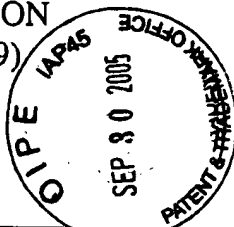
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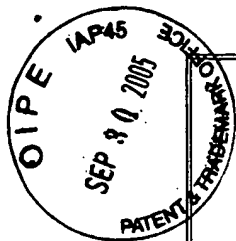
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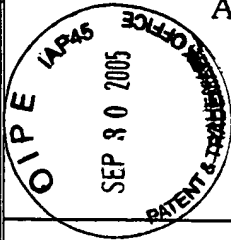
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SHEET 1 OF 1

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)ATTY. DOCKET NO.
005957
USA/Consilium/ConsiliumSERIAL NO.
09/811,667APPLICANT
Huey-Shin YUAN et al.FILING DATE
March 20, 2001GROUP
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
19	5,901,313	05/04/99	Wolf et al.			09/02/97
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19	WO 99/59200	11/18/99	WIPO			X	
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	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
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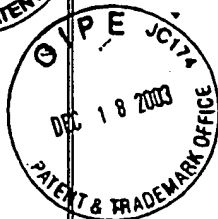
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[Signature]	WO 01/11679	02/15/01	WIPO			X	
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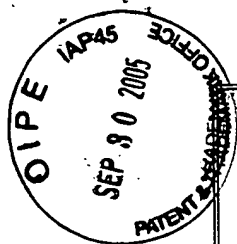
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			11/31/05				

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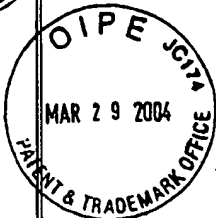
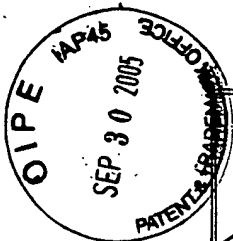
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SHEET 2 OF 2

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(PTO-1449)

ATTY. DOCKET NO.
005957
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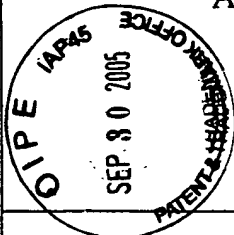
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<i>JS</i>	0 397 924 A1	11/22/90	Europe			X	

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	Rocha, Joao and Carlos Ramos. September 12, 1994. "Task Planning for Flexible and Agile Manufacturing Systems." <i>Intelligent Robots and Systems '94. Advanced Robotic Systems and the Real World, IROS '94. Proceedings of the IEEE/RSJ/GI International Conference on Munich, Germany 12-16 Sept. 1994.</i> New York, New York: IEEE. pp. 105-112.
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DATE CONSIDERED	11/31/05

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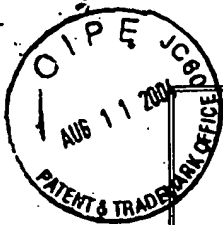
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Huey-Shin YUAN et al.FILING DATE
March 20, 2001GROUP
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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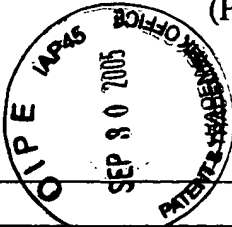
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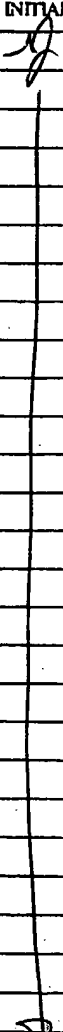
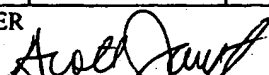
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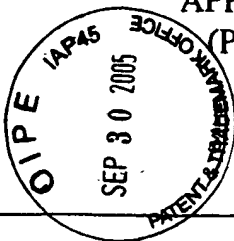
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SHEET 3 OF 4

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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ATTY. DOCKET NO.
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Huey-Shin YUAN et al.

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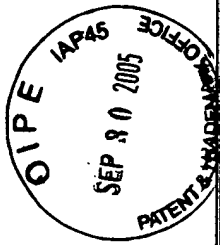
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